

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00578	2.63	0.08679
	Doped silicon	Silicon (Si)	7440-21-3	0.21384	97.37	3.21321
			Subtotal	0.21962	100	3.3
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01373	10.0	0.20624
	Silver alloy	Silver (Ag)	7440-22-4	0.00275	2.0	0.04125
	Lead alloy	Lead (Pb)	7439-92-1	0.12078	88.0	1.8149
			Subtotal	0.13726	100	2.06239
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.28006	100.0	4.20829
			Subtotal	0.28006	100	4.20829
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00978	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00652	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00978	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03585	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.53314	99.81	488.8594
			Subtotal	32.59507	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32276	100.0	4.85
			Subtotal	0.32276	100	4.85
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.31562	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.82065	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.46512	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19934	0.3	2.99532
	Polymer	Epoxy resin system		6.64452	10.0	99.844
			Subtotal	66.44525	100	998.44
			Total	100.00002	100	1502.65069

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